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Advanced High-Speed CMOS Logic AHC / AHCT

Description

Advanced High-Speed CMOS Logic (AHC and AHCT) provide the HCMOS user an excellent migration path to upgrade their speed performance in low power / low noise / low drive applications. AHC devices are fully compatible with CMOS switching levels while AHCT devices are TTL switching level compatible. These technologies have been fully qualified per the requirements of MIL-PRF-38535 (QML).

Performance

- **Speed:** With typical propagation delays of 6.0ns (octals), roughly 3 times faster than HC, AHC is the quick and quiet solution for higher speed operation.
 - **Low Noise:** AHC allows designers who like the low noise characteristics of HCMOS to design at today's performance levels without the overshoot/undershoot problems typical of higher drive devices usually required to achieve AHC speed levels.
 - **Low Power:** AHC averages 40 μ A of static current, half that of HCMOS.
 - **Drive:** Output current is \pm 8mA at 5.0V Vcc and \pm 4mA at 3.3V Vcc.
 - **Technology:** EPIC™ - Enhanced-Performance Implanted CMOS process.
 - **Latch-Up Immunity:** AHC and AHCT exceed 300mA per JEDEC Standard JESD-17.
 - **Pricing:** AHC and AHCT are priced at parity with standard HC and HCT
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Packaging

Package	Ceramic Dual In-Line (CDIP) [J suffix]			Ceramic Leadless Chip Carrier (LCCC) [FK suffix]			Ceramic Flat Package (CFP) [W suffix]		
	Pins	Weight	$R_{\theta_{JA}}$	$R_{\theta_{JC}}$	Weight	$R_{\theta_{JA}}$	$R_{\theta_{JC}}$	Weight	$R_{\theta_{JA}}$
14	2.1	120	28	(*)	(*)	(*)	0.4	180	22
16	2.2	90	28	(*)	(*)	(*)	0.5	165	22
20	3.1	66	28	0.5	65	20	0.6	130	22

Weight.....Typical weight value given is in grams.

$R_{\theta_{JA}}$ Thermal resistance of a package without a path for heat dissipation. This is specified at a zero linear feet per minute air flow. Value given is in °C/W.

$R_{\theta_{JC}}$ Thermal resistance of a package assuming an infinite path for heat dissipation. Value given is in °C/W.

(*) The smallest LCCC available is a 20-pad package.

Applications

AHC and AHCT are well suited for communications and hand-held (battery powered) equipment such as man-pack radios, hand-held FLIRs, helmet-mounted displays, smart munitions and hand-held SAMs.

Literature Information

1997 AHC/AHCT Logic Data Book — Literature Number SCLD003A

1997 SLL CD-ROM — Literature Number SCBC001A

Individual Data Sheets — Available from the TI Product Information Center at (972) 644-5580 or via TI's internet site at

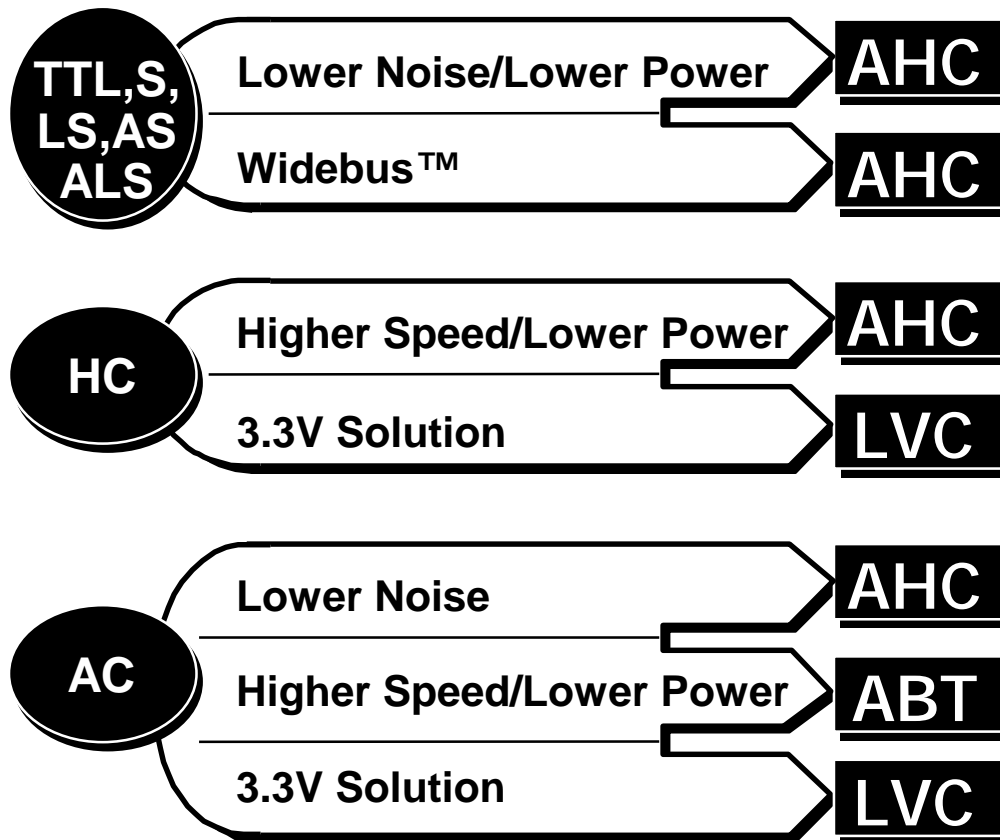
<http://www.ti.com/sc>

Visit the TI Military Semiconductors home page at

<http://www.ti.com/sc/docs/military/welcome.htm>

The chart below shows the various upgrade paths available to the military designer via TI's Advanced Logic solutions:

Logic Migration Chart



Support

For more information on this and other TI logic products, please access our worldwide web site located at www.ti.com or go directly to the URL for TI Military Semiconductors located at www.ti.com/sc/docs/military/welcome.htm.

Receive additional assistance with logic products by calling the Texas Instruments Product Information Center (PIC) during normal business hours (CST/CDT) or the European PIC.

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Product Information Center

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